



INFORMATION DISCLOSURE STATEMENT

It is requested that the following document(s), a copy of which is attached herewith, be notified to the USPTO.

1. Japanese Laid-Open Patent Application No.62-21062

A brief description is provided in the specification.

2. Japanese Laid-Open Patent Application No.61-208223

A brief description is provided in the specification.

A copy of English language Abstract is attached.

3. Japanese Laid-Open Patent Application No.6-37056

A brief description is provided in the specification.

A copy of English language Abstract is attached.

It is not believed that the present invention is disclosed in the document(s) listed above.